Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("5324766").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:14
L2	5	("2717734").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:22
L4	717	(nishida and masahiro).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:23
L5	151	(ishibashi and tatsuo).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:23
L6	38	(okumura and shuzo).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:23
S1	3	"6713161"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/31 13:03
S2	4	(electromagnetic with (sheild$3 or wave-sheild$3 or radiation-sheild$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:12
S3	3	(electromagnetic with (sheild$3 or wave-sheild$3 or radiation-sheild$3)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:21
S4	9	((electromagnetic or radiation) with (sheild$3 or wave-sheild$3 or radiation-sheild$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:12

S5	42	(microwave adj shielding).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:32
S6	686	(radiation adj shielding).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:22
S7	2	S6 and (etch$3 and $7plating and $5resist).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:24
S8	808	(428/203).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:24
S9	2906	(428/209).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:25
S10	1191	(216/41).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:25
S11	992	(216/100).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:25
S12	386	(428/548).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:30
S13	1250	(428/418).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:30
S14	395	(216/12).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:30

S15	88	S14 and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:31
S16	48	S14 and transparent.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:31
S17	12	(((electromagnetic or radiation) near2 shield$3) and (light-transmitting or (light adj transmitting) or transparent) and plat$3 and (resist or photoresist or mask$3) and etch$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/22 17:32
S18	1	("5324766").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/30 19:14
S19	809	(428/203).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:43
S20	2922	(428/209).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22
S21	1201	(216/41).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22
S22	994	(216/100).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22
S23	391	(428/548).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22
S24	1253	(428/418).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22

S25	398	(216/12).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:22
S26	67	(S19 or S20 or S21 or S22 or S23 or S24 or S25) and (electroplat$3 and etch$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:23
S27	551	etch$3 and (electroplat$3 or electroless) and ((resin or polymer or plastic) with hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:28
S28	11	etch$3 and (electroplat$3 or electroless) and ((resin or polymer or plastic) with hydrophilic)	JPO	OR	OFF	2005/05/30 19:47
S29	8	(etch$3 and (electroplat$3 or electroless) and ((resin or polymer or plastic) with hydrophilic)).clm.	US-PGPUB; USPAT	OR	OFF	2005/05/30 19:28
S30	2	etch$3 and (electroplat$3 or electroless) and (resin or polymer or plastic) and hydrophilic and $resist	JPO	OR	OFF	2005/05/30 19:38
S31	5	(etch$3 and (electroplat$3 or electroless) and (resin or polymer or plastic) and hydrophilic and $resist).clm.	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:38
S32	908	(etch$3 and (electroplat$3 or electroless) and (resin or polymer or plastic) and hydrophilic and $resist)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:38
S33	1253	(428/418).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:43
S34	391	(428/548).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:43
S35	1031	(524/431).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:44

S36	376	(264/1.33).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:44
S37	855	(264/1.7).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:44
S38	744	(264/210.2).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:44
S39	203	(427/418).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:44
S40	6	("3753710" | "3773514" | "3775157" | "3839037" | "3874879" | "3900320").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/30 19:45
S41	0	((etch$3 or remov$3) and (plat$3 or electroplat$3 or electroless)).clm. and ((resin or polymer or plastic) with hydrophilic)	JPO	OR	OFF	2005/05/30 19:48
S42	740	((etch$3 or remov$3) and (plat$3 or electroplat$3 or electroless)).clm. and ((resin or polymer or plastic) with hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:48
S43	528	((etch$3 or remov$3) and (plat$3 or electroplat$3 or electroless)).clm. and ((resin or polymer or plastic) near3 hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:48
S44	439	((etch$3 or remov$3) and (plat$3 or electroplat$3 or electroless)).clm. and ((resin or polymer or plastic) near2 hydrophilic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:49
S45	145	S44 not (lithographic or (printing adj plate$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:50

S46	160	S43 not (lithographic or (printing adj plate$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:52
S47	72	black adj (electroplat$3 or electroless)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/30 19:53